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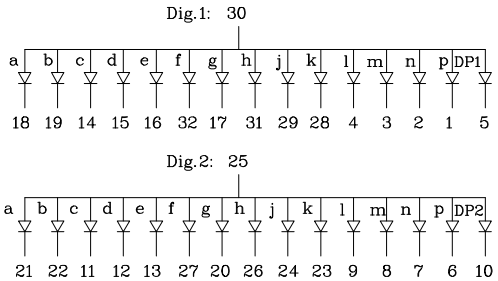
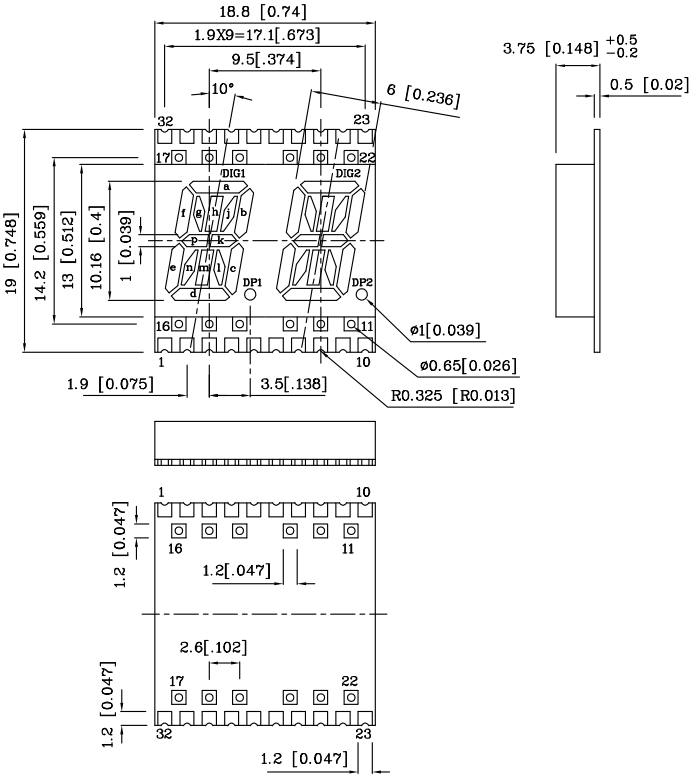
Part Number: **XZAMDK10A2**

SURFACE MOUNT DISPLAY

Features

- 0.4 INCH CHARACTER HEIGHT.
- LOW CURRENT OPERATION.
- HIGH CONTRAST AND LIGHT OUTPUT.
- EASY MOUNTING ON P.C. BOARDS OR SOCKETS.
- CATEGORIZED FOR LUMINOUS INTENSITY.
- MECHANICALLY RUGGED.
- GRAY FACE, WHITE SEGMENT.
- PACKAGE :500PCS / REEL.
- RoHS COMPLIANT.





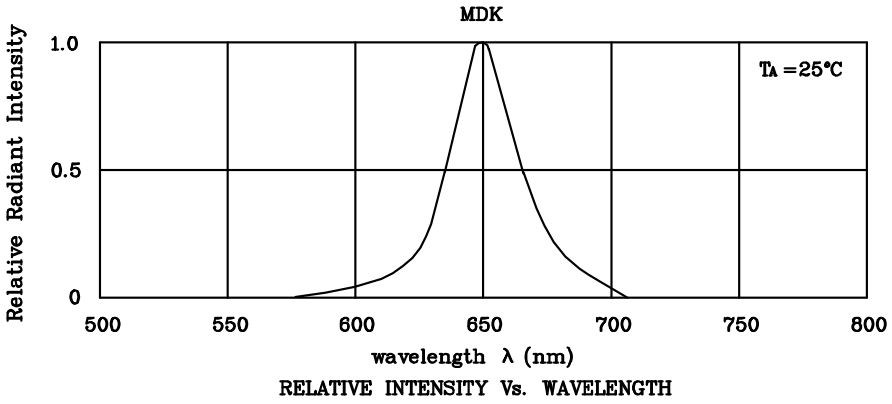
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.25(0.01") unless otherwise noted.

Absolute maximum ratings (TA=25°C)		**MDK (InGaAlP)**	**Unit**
Reverse Voltage	VR	5	V
Forward Current	IF	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	iFS	185	mA
Power Dissipation	PT	75	mW
Operating Temperature	TA	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	

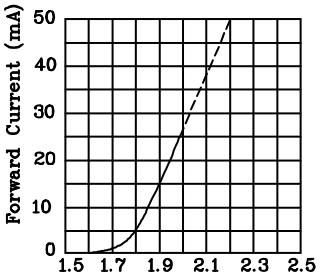
Operating Characteristics (TA=25°C)		**MDK (InGaAlP)**	**Unit**
Forward Voltage (Typ.) (IF=10mA)	VF	1.85	V
Forward Voltage (Max.) (IF=10mA)	VF	2.5	V
Reverse Current (VR=5V)	IR	10	uA
Wavelength of Peak Emission (IF=10mA)	λ P	650	nm
Wavelength of Dominant Emission (IF=10mA)	λ D	635	nm
Spectral Line Full Width At Half-Maximum (IF=10mA)	Δλ	28	nm
Capacitance (VF=0V, f=1MHz)	C	35	pF

Part Number	Emitting Color	Emitting Material	Luminous Intensity (IF=10mA) ucd		Wavelength nm λ P	Description
			min.	typ.		
XZAMDK10A2	Red	InGaAlP	4700	22790	650	Common Anode, Rt. Hand Decimal

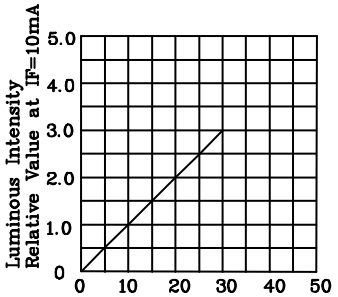


RELATIVE INTENSITY Vs. WAVELENGTH

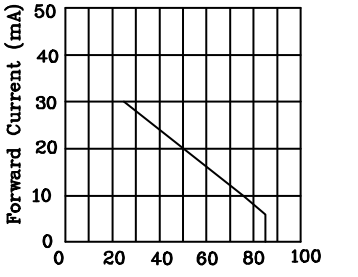
❖ **MDK**



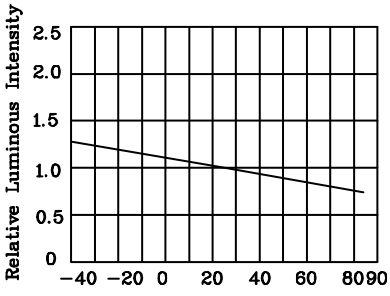
FORWARD CURRENT Vs.
FORWARD VOLTAGE



LUMINOUS INTENSITY Vs.
FORWARD CURRENT



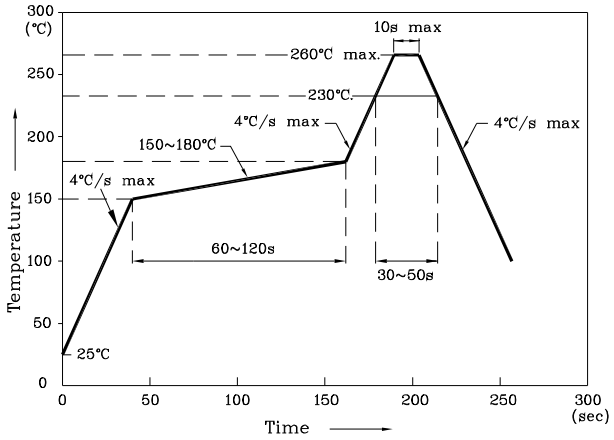
FORWARD CURRENT
DERATING CURVE



LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE

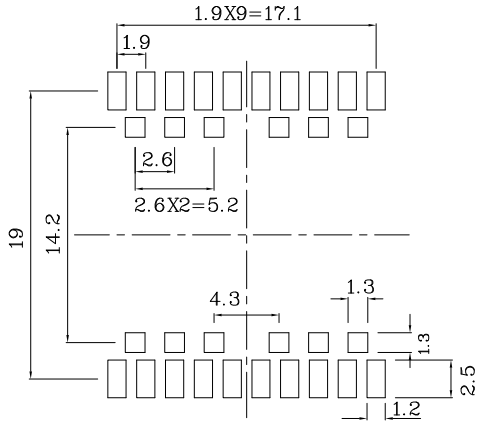
Remarks:
If special sorting is required (e.g. binning based on forward voltage, luminous intensity or wavelength),
the typical accuracy of the sorting process is as follows:
1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%
3. Forward Voltage: +/-0.1V
Note: Accuracy may depend on the sorting parameters.

Reflow Soldering Profile For Lead-free SMT Process.



Notes:
1. Maximum soldering temperature should not exceed 260℃.
2. Recommended reflow temperature: 145℃-260℃.
3. Do not put stress to the epoxy resin during high temperatures conditions.

❖ Recommended Soldering Pattern (Units : mm;Tolerance: ± 0.15)



❖ Tape Specification (Units : mm)